

PCN Number:	20230721002.1			PCN Date:	July 27, 2023								
Title:	Qualification of additional mold compound for select devices												
Customer Contact:	Change Management Team		Dept:	Quality Services									
Proposed 1st Ship Date:	Oct 27, 2023			Sample requests accepted until:	Aug 27, 2023								
*Sample requests received after Aug 27, 2023 will not be supported.													
Change Type:													
☐	Assembly Site	☐	Design	☐	Wafer Bump Material								
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process								
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site								
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material								
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process								
PCN Details													
Description of Change:													
This PCN is to inform of an alternate mold compound qualification for the devices listed below as follows:													
<table border="1"> <thead> <tr> <th>What</th> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#402042101</td> <td>S#131010100089</td> </tr> </tbody> </table>		What	Current	New	Mold Compound	SID#402042101	S#131010100089						
What	Current	New											
Mold Compound	SID#402042101	S#131010100089											
Reason for Change:													
Continuity of supply													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Impact on Environmental Ratings													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </tbody> </table>		RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474										
☒ No Change	☒ No Change	☒ No Change	☒ No Change										
Changes to product identification resulting from this PCN:													
Not applicable													
Product Affected:													
BQ2022ALPR	TL431ACLP	TL431AILPM	TL431CLPM										
LP2950-50LPRE3	TL431ACLPM	TL431AILPM-NT2	TL431CLPR										
TL1431CLP	TL431ACLPR	TL431AILPR	TL431ILP										
TL1431CLPME3	TL431AILP	TL431CLP	TL431ILPR										
TL1431CLPR													

Qualification Report

ATXWH TO92 new compound Qual
Approve Date 05-July-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TL1431CLP	Qual Device: BQ2022ALPR	Qual Device: LP2950-50LPRE3
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-
FTY	E6	Final Test Yield	-	-	3/3/0	1/1/0	1/1/0

- QBS: Qual By Similarity
- Qual Device TL1431CLP is qualified at NOT CLASSIFIED NOT CLASSIFIED
- Qual Device BQ2022ALPR is qualified at NOT CLASSIFIED NOT CLASSIFIED
- Qual Device LP2950-50LPRE3 is qualified at NOT CLASSIFIED NOT CLASSIFIED
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2209-067

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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